DATE: 05/20/2004

cosmo

ELECTRONICS CORPORATION

SMD LED:

KL-170YGX

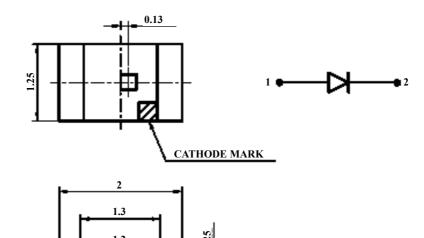
NO. 61L20001 REV.

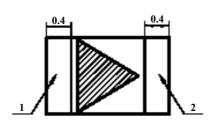
SHEET 1 OF 9

1

UNIT:MM

TOLERANCE: ±0.15





Part No.	Emitting Color	Material	Lens Type		V 0mA) TYP (mcd)	Viewing Angle 2 θ 1/2
KL-170YGX	Green	GaP	Water Clear	5	12	120°

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KL-170YGX

NO. 61L20001

SHEET 2 OF 9

REV.

Absolute maximum ratings (TA=25°C)		G Green (GaP)	Unit
Reverse voltage	VR	5	V
Forward current	IF	25	mA
Forward current(Peak)	IFP	100	mA
1/10 Duty Cycle,0.1ms Pulse Width			
Power dissipation	$\mathbf{P}_{\mathbf{d}}$	40	mW
LED LAMPS:			
Operating temperature	Тор	-40~+85	$^{\circ}$
Storage temperature	Tst	-40~+85	${\mathbb C}$
LED DISPLAYS:			
Operating temperature	TA	-40~+85	$^{\circ}$
Storage temperature	Tstg	-40~+85	$^{\circ}$

Operating characteristics (TA=25°C)		G Green (GaP)	Unit
Forward voltage(typ.) IF=20mA	VF	2.2	V
Forward voltage(max.) IF=20mA	$\mathbf{V}_{\mathbf{F}}$	2.6	V
Reverse current(max.) V _R =5V	IR	10	uA
Wavelength at dominant emission(typ.) IF=20mA	λъ	570	nm
Wavelength at peak emission(typ.)	λР	568	nm
IF=20mA Spectral line half-width IF=20mA	Δλ	30	nm
Capacitance V _F =0V,f=1MHz	C	45	pF

DATE: 05/20/2004

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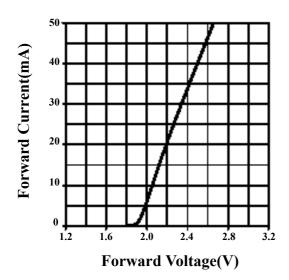
KL-170YGX

NO.61L20001

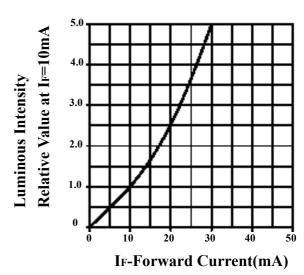
REV.

SHEET 3 OF 9

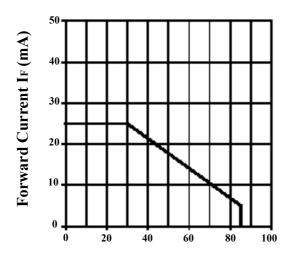
1



Forward Current Vs. **Forward Voltage**



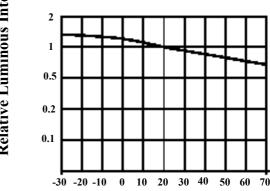
Luminous Intensity Vs. **Forward Current**



Forward Current Derating Curve

Ambient Temperature T_A(°C)





Ambient Temperature T_A(°C)

Luminous Intensity Vs. **Ambient Temperature**

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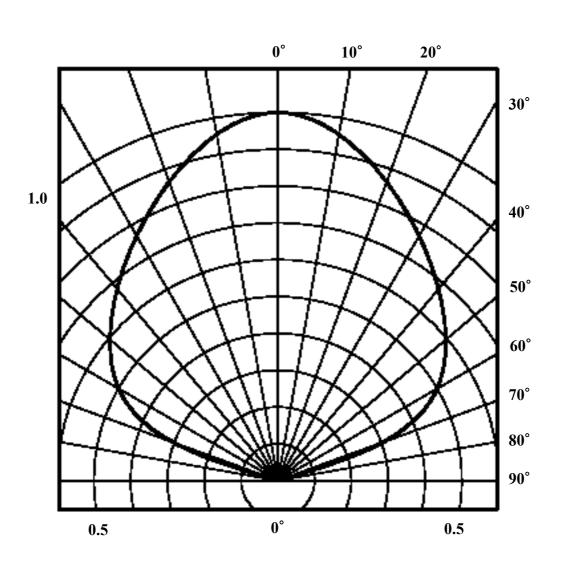
SMD LED:

KL-170YGX

NO. 61L20001

SHEET 4 OF 9

REV.



View Angle 2 *∂* 1/2=120°

DATE: 05/20/2004

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SMD LED:

KL-170YGX

NO. 61L20001

REV.

SHEET 5 OF 9

1

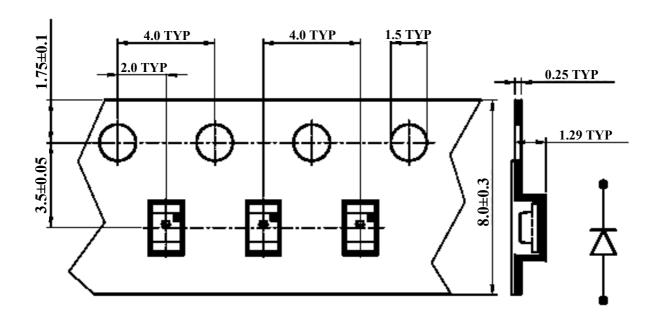
UNIT:MM

TOLERANCE: ±0.25

TYPE ->

PACKAGE:2000 OR 1000PCS/REEL

REEL"T":14mmTYP



DATE: 05/20/2004

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SMD LED:

KL-170YGX

NO. 61L20001

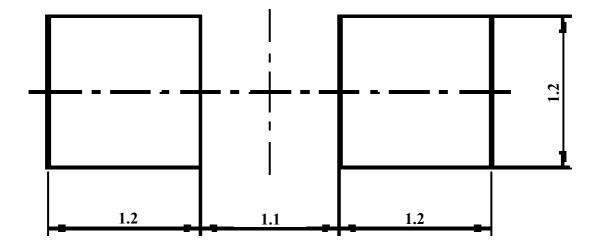
REV. 1

SHEET 6 OF 9

UNIT:MM

The following soldering patterns are recommended for reflow-soldering:

For reflow soldering



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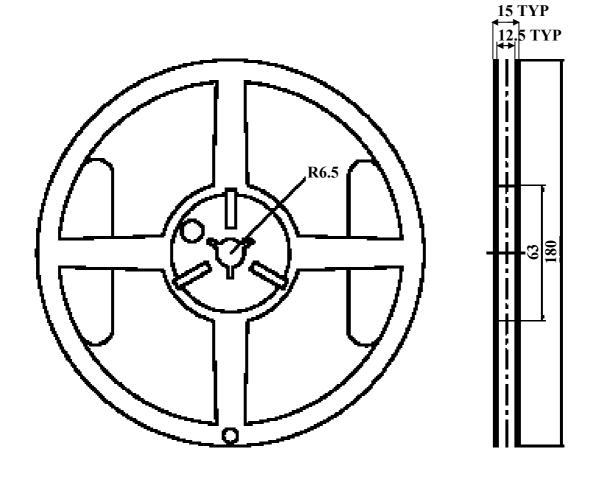
REV.

SHEET 7 OF 9

1

UNIT:MM

TOLERANCE: ±0.25



DATE: 05/20/2004

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SMD LED:

KL-170YGX

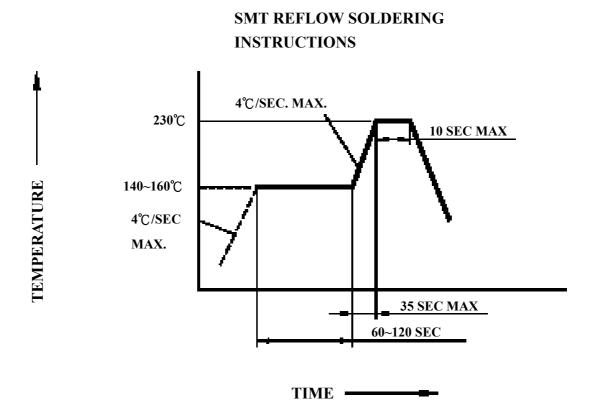
NO. 61L20001

REV.

SHEET 8 OF 9

1

SOLDERING



SOLDERING INSRTUCTIONS							
TYPES	DIP AND WAVE SOLDERING			IRON SOLDERING(WITH 1.5mm IRON TIP)			
	TEMPERATURE OF THE SOLDERING BATH	MAXLMUM SOLDERING TIME	DISTANCE FORM SOLDER JOINT TO CASE	TEMPERATURE OF SOLDERING IRON	MAXLMUM SOLDERING TIME	DISTANCE FROM SOLDER JOINT TO CASE	
LEDS	≦260 ℃	38	>2mm	≦260 ℃	38	>2mm	
	≦260 ℃	5 S	>4mm	≦260 ℃	58	>4mm	
DISPLAYS	≦260 ℃	3S	>2mm	≦260 ℃	38	>2mm	
			•				

DATE: 05/20/2004

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NO. 61L20001

REV.

SHEET 9 OF 9

1

SMD HANDLING AND APPLICATION PRECAUTIONS

STORAGE

(1.1)It is recommended to store the devices in accordance with the following conditions:

Humidity: 60%RH Max.

Temperature: $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ ($41^{\circ}\text{F} \sim 86^{\circ}\text{F}$)

(1.2)Shelf life in sealed bag: 12 month at $<5^{\circ}\text{C} \sim 30^{\circ}\text{C}$ and <30%RH.

After the package is opened, the products should be used within 72hrs.

Or they should be kept at $\leq 20\%\text{RH}$ in zip -locked sealed bags.

DRY PACK AND BAKING

SMD LEDs are MOISTURE SENSITIVE devices. Avoid absorbing moisture at any time during transportation and/or storage. It is recommended to bake before soldering when the pack is unsealed after 72 hrs, or any suspicious moisture being found. Bake devices in accordance with the following conditions:

- (a) $60\pm3^{\circ}$ C x (12~24hrs) and <5%RH, taped reel type
- (b) $100\pm3^{\circ}$ C x (45min~1hr), loose packing type, or
- (c) $130\pm3^{\circ}$ C x (15~30min), loose packing type

ELECTRIC STATIC DISCHARGE(ESD) PROTECTION

Materials with GaN, InGaN, AlInGaP are STATIC SENSITIVE devices. They will be packed in anti-static bags. ESD protection must be deliberatively observed from the initial design stage. The static -electric discharge may result in severe malfunction of the devices. In the events of manual working in process, make sure the devices are well protected from ESD at any time. Surge before and during handling products.